

1 - 4 September 2025 Tokyo Japan CALL FOR ABSTRACT Submission Deadline: 15 May 2025

The 13th International Conference on Porous Metals and Metallic Foams (MetFoam 2025) is the largest cross-disciplinary, international technical meeting focused exclusively on the production, properties, and application of light weight porous/cellular metals.

Plan to be part of this not-to-be-missed event! Connect with other experts in the field by submitting your abstract for consideration by 15 May 2025.

Topics planned for MetFoam 2025 include, but are not limited to: Germany

- Research in fabrication of porous/cellular metals by conventional and novel methods including additive manufacturing
- Characterization and properties of cellular metals
- · Design and simulation of open and closed cell porous metals
- Porous metallic biomaterials
- Nanoporous metals
- Application studies and industrial applications of porous metals and metallic foams

Important Dates

Venue

15th MayAbstracts
deadline1st Sep.Registration2nd ~ 4th Sep.Sessions

Waseda University, Nishi-waseda Campus 3-4-1 Okubo, Shinjuku ward, Tokyo, Japan

Website and Contact information

You may submit your abstract and registration via website <http://www.metfoam2025.com/> which will be launched at the end of March.

If you have any questions, feel free to email our office. <metfoam-office@metfoam2025.com> (Dr. Takamatsu or Dr. Shiinoki)

An abstract template is available here(pw: MetFoam2025Japan) S https://waseda.box.com/v/metfoam-2025-for-participants

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